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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re PATENT APPLICATION of

Toshihiko Iwakiri

Group Art Unit: 2827

Serial No.: 09/866,920

Examiner: L. Cruz

Filed: May 30, 2001

For: SEMICONDUCTOR DEVICE HAVING A DIE PAD SUPPORTED BY A DIE PAD SUPPORTER

AMENDMENT

Honorable Assistant Commissioner for Patents
Washington, D.C. 20231

Date: October 28, 2002
(Monday)

Sir:

In response to the Office Action dated June 27, 2002, the period for response having been extended one month to October 27, 2002, the following amendments and remarks are respectfully submitted in connection with the above-identified application.

In the Abstract:

Please cancel the Abstract and replace with the Abstract attached herewith.

In the Specification:

Replace the paragraph beginning on page 3, line 19 with the following paragraph:

“As shown in Fig. 1, a die pad 2 is formed at a central portion of a leadframe 1.

Four die pad supporters 3 support the die pad 2. The die pad supporters 3 are located

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